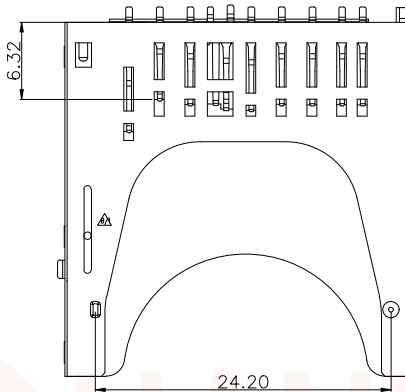
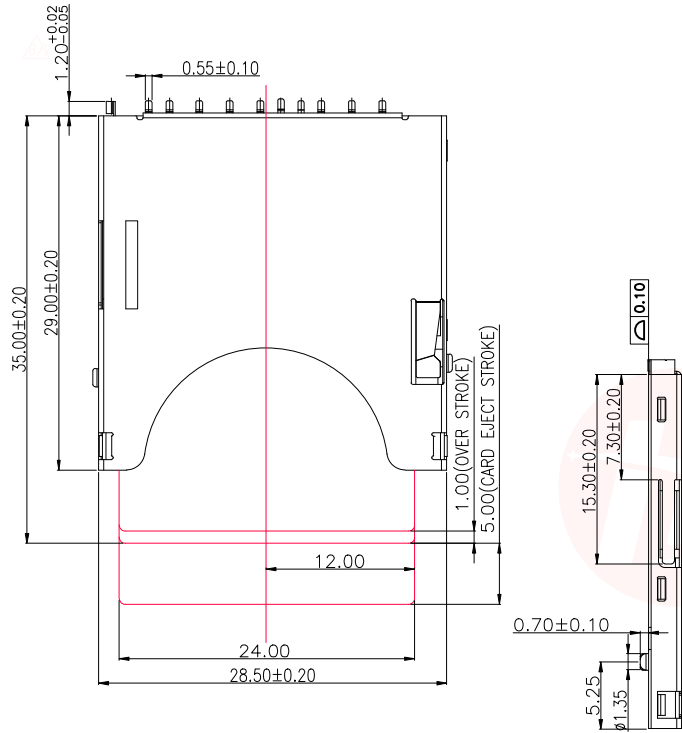




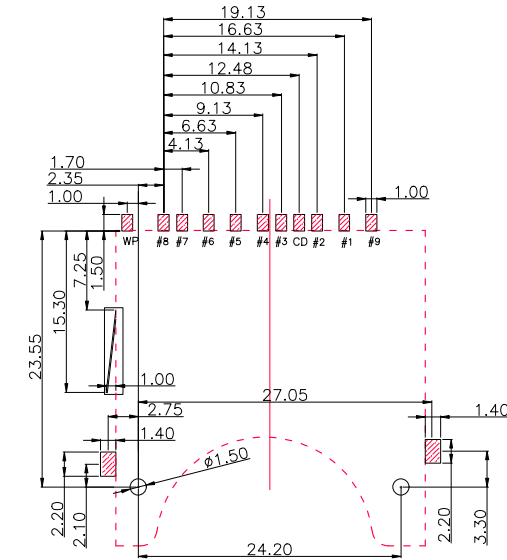
REV.	ECN NO OR DESCRIPTION	REVISED	DATE

Specification

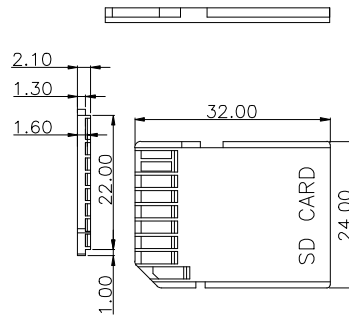
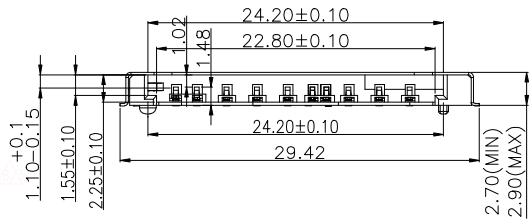
- 1.MATERIAL:
- 1.1 Insulator:High Temperature Thermoplastic, (LCP E130I),UL Black 94V-0.
 - 1.2 Contact: Phosphor Bronze(C5191-EH,T=0.15±0.03mm)
 - 1.3 Shell: SUS301-3/4H T=0.20±0.01mm
- 2.Plating:
- 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 80u"min Sn over Ni on solder area
 - 2.2 Shell: Plated 50u"min Ni Overall
- 3.Electrical:
- 3.1 Current Rating :0.5A AC/DC max.
 - 3.2 Voltage Rating :12V AC/DC
 - 3.3 Ambient Temperature Range :-20°C~+60°C
 - 3.4 Storage Temperature Range :-40°C~+70°C
 - 3.5 Ambient Humidity Range :95% R.H. Max.
 - 3.6 Contact Resistance:100mΩ max.
 - 3.7 Insulation Resistance:1000MΩ min./500VDC
 - 3.8 Mating Cycles:5,000 Insertions
- 4.Usable Memory Card:SD&MMC Card



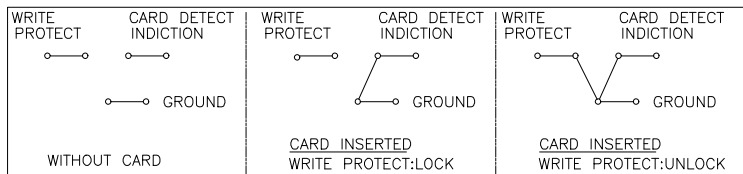
PIN NO.	NAME	TYPE	DESCRIPTION
#1	CD/DAT3	I/O/PP	CARD DETECT/DATA LINE(BIT3)
#2	CMD	PP	COMMAND/RESPONSE
#3	VSS1	S	SUPPLY VOLTAGE GROUND
#4	VDD	S	SUPPLY VOLTAGE
#5	CLK	I	CLOCK
#6	VSS2	S	SUPPLY VOLTAGE GROUND
#7	DAT0	I/O/PP	DATA LINE(BIT 0)
#8	DAT1	I/O/PP	DATA LINE(BIT 1)
#9	DAT2	I/O/PP	DATA LINE(BIT 2)



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



CIRCUIT:



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X.X ±0.35, X.XX ±0.25, X.XXX ±0.15

ANGLES: .X ±5°, .XX ±3°

东 莞 市 汉 博 电 子 科 技 有 限 公 司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE: SD CARD CONN PUSH SMT

DWN: xiong SD-111

CHKD: lee SCALE:1:1 UNIT: mm

APVD: wang SIZE: A4 SHEET:1OF 1 REV: A4

CUSTOMER COPY